	Hits	Search Text	DBs
28	0	((expos$4 or illuminat$4 or irradia$5) same (photoresist or resist or (radiation near4 sensitiv$4))) and ((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (pattern$4 or structure) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree"))) and ((pattern or pitch or line$3width) same (50nm or ("500" near9 angstrom)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
29	1	"430"/$.ccls. and ((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild)))) and ((pitch or linewidth or hole or pattern) same (50nm or "50A" or ("50" near4 angstrom)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
30	4	((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild)))) and ((pitch or linewidth or hole or pattern) same (50nm or "50A" or ("50" near4 angstrom)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
31	1	((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild)))) and ((pitch or linewidth or hole or pattern) same (50nm or "50A" or ("50" near4 angstrom)))	US-PGPUB

	Hits	Search Text	DBs
32	1	((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild)))) and ((pitch or linewidth or hole or pattern or feature) same (50nm or "50A" or ("50" near4 angstrom) or ("50" near5 half$3pitch)))	US-PGPUB
33	3	430/313.ccls. and ((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
34	11	430/330.ccls. and ((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
35	12	430/325.ccls. and ((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
36	1	((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild)))) and ((pitch or linewidth or hole or pattern) same (50nm or "50A" or ("50" near4 angstrom) or ("500" near4 Angstroms)))	US-PGPUB
37	1	((heat$3 or bak$3 or thermal$3treat$4 or (thermal$3 near3 process$4) or post$4bak$3 or PEB or post$4expos$4bak$4) same (humid$3 or water or moisture or atmosphere or ambient) same (resist or photoresist) same (expos$3 or irradiat$3 or illuminat$4) same (("20" adj "degree") or ("50" adj "degree") or ("30" adj "degree") or ("35" adj "degree") or ("25" adj "degree") or ("40" adj "degree") or ("45" adj "degree") or (temperature near6 (low$2 or mild)))) and ((pitch or linewidth or hole or pattern or feature or (half near3 pitch)) same (50nm or "50A" or ("50" near4 angstrom) or ("500" near4 Angstroms)))	US-PGPUB